

1. General description

Standard power diode (unsawn wafer).

2. Features and benefits

- Low Forward Voltage Drop
- Low leakage current
- High voltage capability
- High inrush current capability

3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RRM}^*	repetitive peak reverse voltage		-	-	1600	V
$I_{F(AV)}^{**}$	average forward current	$\delta = 0.5$; square-wave pulse	-	-	35	A
Static characteristics						
V_F^{**}	forward voltage	$I_F = 35\text{ A}$; $T_j = 25\text{ °C}$	-	1.15	1.2	V

4. Ordering information

Table 2. Ordering information

Product type	Orderable part number	Description	Packing method
WB35SD160AL	WB35SD160ALZ	Bare die on wafer	Unsawn wafer, Vacuum packing

5. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}^*	repetitive peak reverse voltage		-	1600	V
V_{RWM}^*	crest working reverse voltage		-	1600	V
V_R^*	reverse voltage	DC	-	1600	V
$I_{F(AV)}^{**}$	average forward current	$\delta = 0.5$; square-wave pulse	-	35	A
I_{FRM}^{**}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25 \mu s$; square-wave pulse	-	70	A
I_{FSM}^{**}	non-repetitive peak forward current	$t_p = 10 \text{ ms}$; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$; sine-wave pulse	-	450	A
		$t_p = 8.3 \text{ ms}$; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$; sine-wave pulse	-	494	A
T_{stg}^{**}	storage temperature		-40	150	$^\circ\text{C}$
T_j^{**}	junction temperature			150	$^\circ\text{C}$

6. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F^{**}	forward voltage	$I_F = 35 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$	-	1.15	1.2	V
		$I_F = 35 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$	-	1.1	1.15	V
I_R^*	reverse current	$V_R = 1600 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	-	50	μA
		$V_R = 1600 \text{ V}$; $T_j = 125 \text{ }^\circ\text{C}$	-	-	1	mA
I_R^{**}	reverse current	$V_R = 1600 \text{ V}$; $T_j = 150 \text{ }^\circ\text{C}$	-	-	1.5	mA

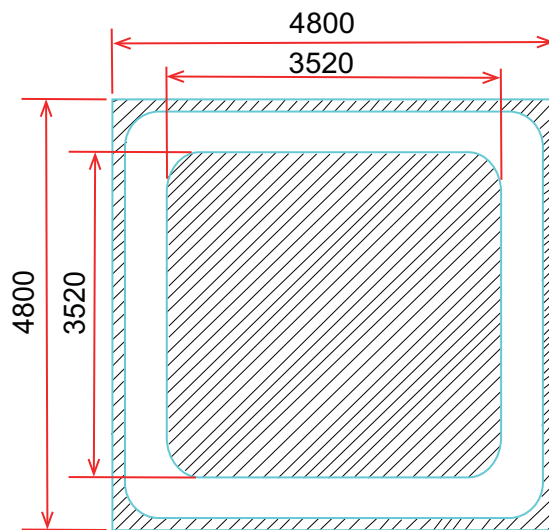
Notes:

(1) * mean that parameter are 100% test at $T_{amb} = 25^\circ\text{C}$

(2) ** means that the guaranteed ratings and parameter limits will depend on the assembled structure. When correctly assembled with suitable die bonding and wire bonding, the device will have ratings and characteristics guaranteed in this data sheet, similar to the assembled devices.

MECHANICAL PATAMETER		
Chip size	4.8 x 4.8	mm ²
Anode pad size	3.52 x 3.52	mm ²
Area total / active	23.04 / 12.39	mm ²
Thickness	300	μm
Wafer size	125	mm
Max possible chips per wafer	465	pcs
Passivation	Planar	
Front metal	Al	
Back metal	Ti Ni Ag	

CHIP LAYOUT



Die size: 4800μm x 4800μm
Bond pad size: 3520μm x 3520μm

7. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.ween-semi.com>.

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